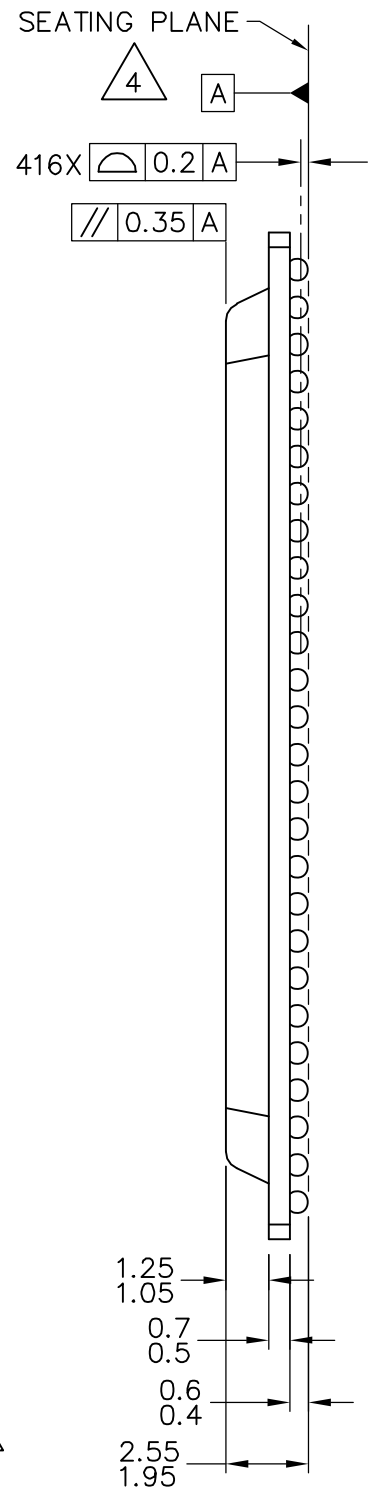
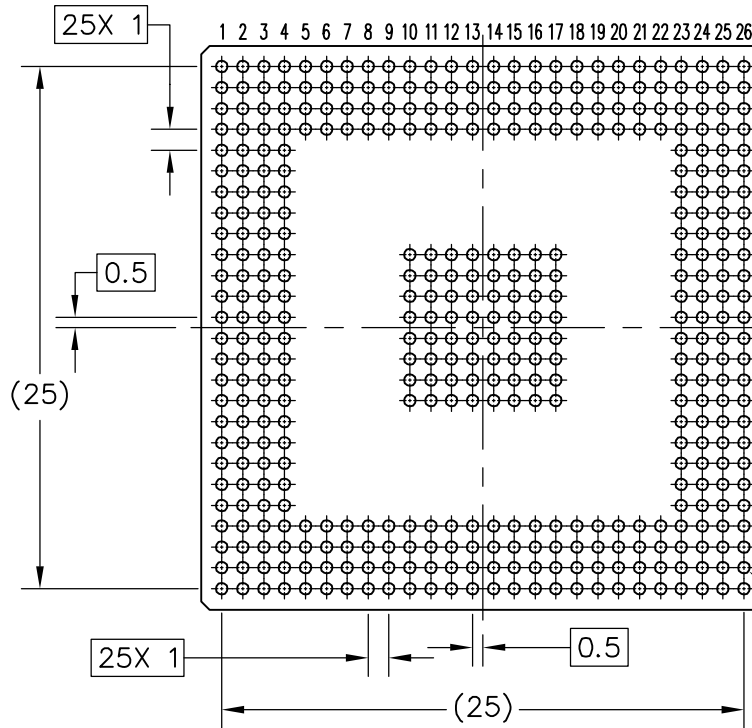


TOP VIEW



SIDE VIEW



BOTTOM VIEW

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TITLE: 416 I/O, PBGA 27 X 27 PKG, 1 MM PITCH (OMPAC)		DOCUMENT NO: 98ARE10523D		REV: A	
		CASE NUMBER: 1494-01		13 JUL 2005	
		STANDARD: JEDEC MS-034 AAL-1			

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

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